

**IN THE SPECIFICATION**

Please amend the title from "DISPLAY APPARATUS AND METHOD FOR FABRICATING THE SAME" to read -DISPLAY APPARATUS WITH RIBS HAVING CONDUCTIVE MATERIAL--.

Please substitute the paragraph beginning on page 10, line 1 with the following paragraph:

Next, on the substrate 1, a first interlayer insulating film 4 made of silicon oxide or a silicon oxide-base material such as PSG (phospho-silicate glass), that is phosphorus-containing silicon oxide, is formed so as to cover the thin-film transistor 2. The first interlayer insulating film 4 is then processed to form via holes (not shown) thereon, a wiring 6 is then patterned on the first interlayer insulating film 4 so as to make contact with each of the two a source/drain regions of the thin-film transistor 2 through the via holes and to form a first electrode 6A (e.g., a source electrode) and a second electrode 6B (e.g., a drain electrode) to respectively provide electrical connection to the two source/drain regions. The wiring 6 is used for a signal line and is made, for example, of aluminum-copper alloy.

Please substitute the paragraph beginning on page 10, line 13 with the following paragraph:

Next, as shown in Fig. %[FillPoint] 3B, a second interlayer insulating film 7 is formed on the first interlayer insulating film 4 so as to cover the wiring 6 (and both the source and drain electrodes (e.g., 6A and 6B) of the thin film transistor 2), and the second interlayer insulating film 7 is then processed to form via holes 8 thereon, the bottom of which reaches the wiring 6 for one of the source and drain electrodes (e.g., 6A and 6B). The second interlayer insulating film 7

is preferably made of a material film which can readily be planarized such as polyimide film since the film covers the patterned wiring 6. The second interlayer insulating film 7 is also preferably made of a material film with a small coefficient of water absorption since the second interlayer insulating film 7 is expected to prevent moisture-related deterioration of an organic layer formed later and thereby to retain desirable luminous intensity.

Please substitute the paragraph beginning on page 12, line 2 with the following paragraph:

More specifically, first as shown in Fig. 3C, the lower electrode 10 patterned for every pixel "a" is formed on the second interlayer insulating film 7 so as to make contact with the wiring 6 for one of the source and drain electrodes (e.g., 6A and 6B) through the via hole 8 formed to the second interlayer insulating film 7. The lower electrode 10 is used as an anode electrode or a cathode electrode, which is made of a highly reflective material when the display apparatus is designed as a top emission type, whereas made of a transparent material for the display apparatus of transmission type.

Please substitute the paragraph beginning on page 13, line 6 with the following paragraph:

Next, as shown in Figs. 5A, 5B and 5C, the organic layers 11R, 11G and 11B corresponded to each emission color are successively formed on the lower electrode 10 for each pixel "a". More specifically, a metal mask 20 having openings arranged in a pattern corresponded to each color of the pixels is placed on the rib 14 as a spacer, and the individual organic layers 11R, 11G, 11B are successively evaporated on the lower electrode 10. The individual organic layers 11R, 11G, 11B are formed so as to fully cover the exposed portion of the lower electrode 10, and are

practically composed of, ~~although not shown in figure,~~ an organic hole transport layer (22 in Fig. 5D), an organic light emitting layer (24 in Fig. 5D) and an optional organic electron transport layer (26 in Fig. 5D) stacked, as occasion arises, in this order from the lower electrode 10 side.